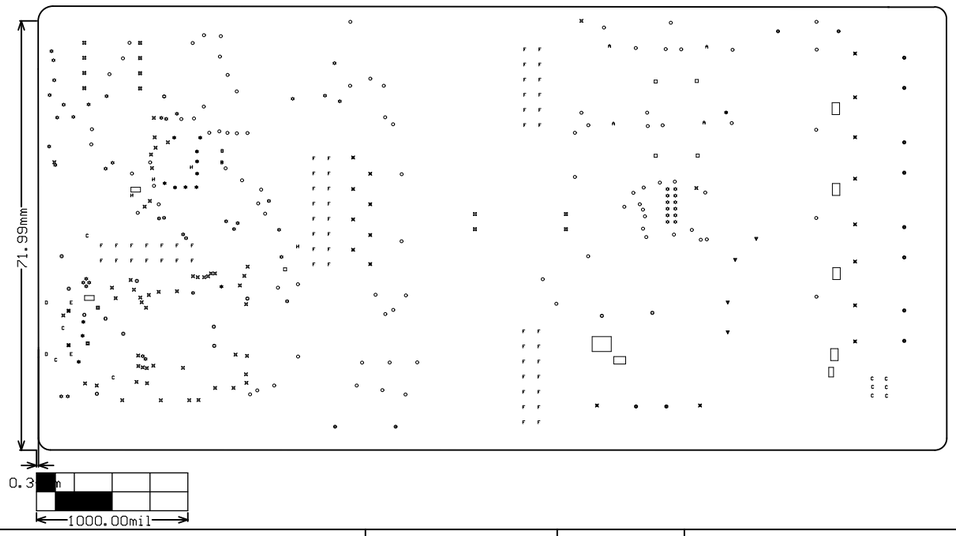
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		2.76mil		
	Dielectric1	FR-4 High Tg	59.20mil	4.8	
2	Mid-Layer 1		1.40mil		
	Dielectric2	FR-4	12.60mil	4.8	
3	Mid-Layer 2		1.40mil		
	Dielectric3	FR-4	12.60mil	4.8	
4	Bottom Layer		2.76mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
	52	0.200mm (7.87mil)	PTH	Round	Top Layer - Bottom Layer	
	52	0.203mm (8.00mil)	PTH	Round	Top Layer - Bottom Layer	
H	4	0.300mm (11.81mil)	PTH	Round	Top Layer - Bottom Layer	
	14	0.305mm (12.00mil)	PTH	Round	Top Layer - Bottom Layer	
	13	0.356mm (14.00mil)	PTH	Round	Top Layer - Bottom Layer	
C	10	0.381mm (15.00mil)	PTH	Round	Top Layer - Bottom Layer	
B	2	0.400mm (15.75mil)	PTH	Round	Top Layer - Bottom Layer	
O	90	0.406mm (16.00mil)	PTH	Round	Top Layer - Bottom Layer	
	2	0.465mm (18.29mil)	PTH	Round	Top Layer - Bottom Layer	
	2	0.650mm (25.59mil)	NPTH	Round	Top Layer - Bottom Layer	
A	4	0.700mm (27.56mil)	PTH	Round	Top Layer - Bottom Layer	
	4	0.900mm (35.43mil)	PTH	Round	Top Layer - Bottom Layer	
	5	1.016mm (40.00mil)	PTH	Round	Top Layer - Bottom Layer	
F	56	1.100mm (43.31mil)	PTH	Round	Top Layer - Bottom Layer	
	12	1.150mm (45.28mil)	PTH	Round	Top Layer - Bottom Layer	
	4	1.300mm (51.18mil)	PTH	Round	Top Layer - Bottom Layer	
D	2	1.400mm (55.12mil)	PTH	Slot	Top Layer - Bottom Layer	
	10	1.500mm (59.06mil)	PTH	Round	Top Layer - Bottom Layer	
	18	1.600mm (63.00mil)	PTH	Round	Top Layer - Bottom Layer	
E	2	1.700mm (66.93mil)	PTH	Slot	Top Layer - Bottom Layer	
	358 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout



DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 7.874 MIL
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-4 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: DRV81646DGQ
DESIGNED FOR: Public Release
FILE NAME: MD108_DRV81646DGQ.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: MD108-001	REV: A	SUN REV: Not in version control
LAYER NAME = [illegible]	TID #: N/A		
PLOT NAME = Fabrication Drawing	GENERATED : 10/31/2025 1:40:58 PM		TEXAS INSTRUMENTS

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ENGINEER:	LAYOUT BY:
Mojtaba Afshar	Mojtaba Afshar
SCALE: 1.00	ALTIUM DESIGNER VERSION: 23.1.1.15